



Material Content Data Sheet



Sales Product Name		IPD60R180C7		Issued		16. March 2016		
MA#		MA001487758						
Package		PG-TO252-3-341		Weight*		390.11 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.951	1.01	1.01	10128	10128
leadframe	non noble metal	iron	7439-89-6	0.248	0.06		637	
	inorganic material	phosphorus	7723-14-0	0.075	0.02		191	
	non noble metal	copper	7440-50-8	248.124	63.61	63.69	636042	636870
wire	non noble metal	aluminium	7429-90-5	15.873	4.07	4.07	40689	40689
encapsulation	organic material	carbon black	1333-86-4	0.343	0.09		878	
	plastics	epoxy resin	-	10.393	2.66		26641	
	inorganic material	silicondioxide	60676-86-0	103.470	26.52	29.27	265236	292755
leadfinish	non noble metal	tin	7440-31-5	3.740	0.96	0.96	9587	9587
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1304	1304
solder	noble metal	silver	7440-22-4	0.085	0.02		217	
	non noble metal	tin	7440-31-5	0.068	0.02		173	
	non noble metal	lead	7439-92-1	3.229	0.83	0.87	8277	8667
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com